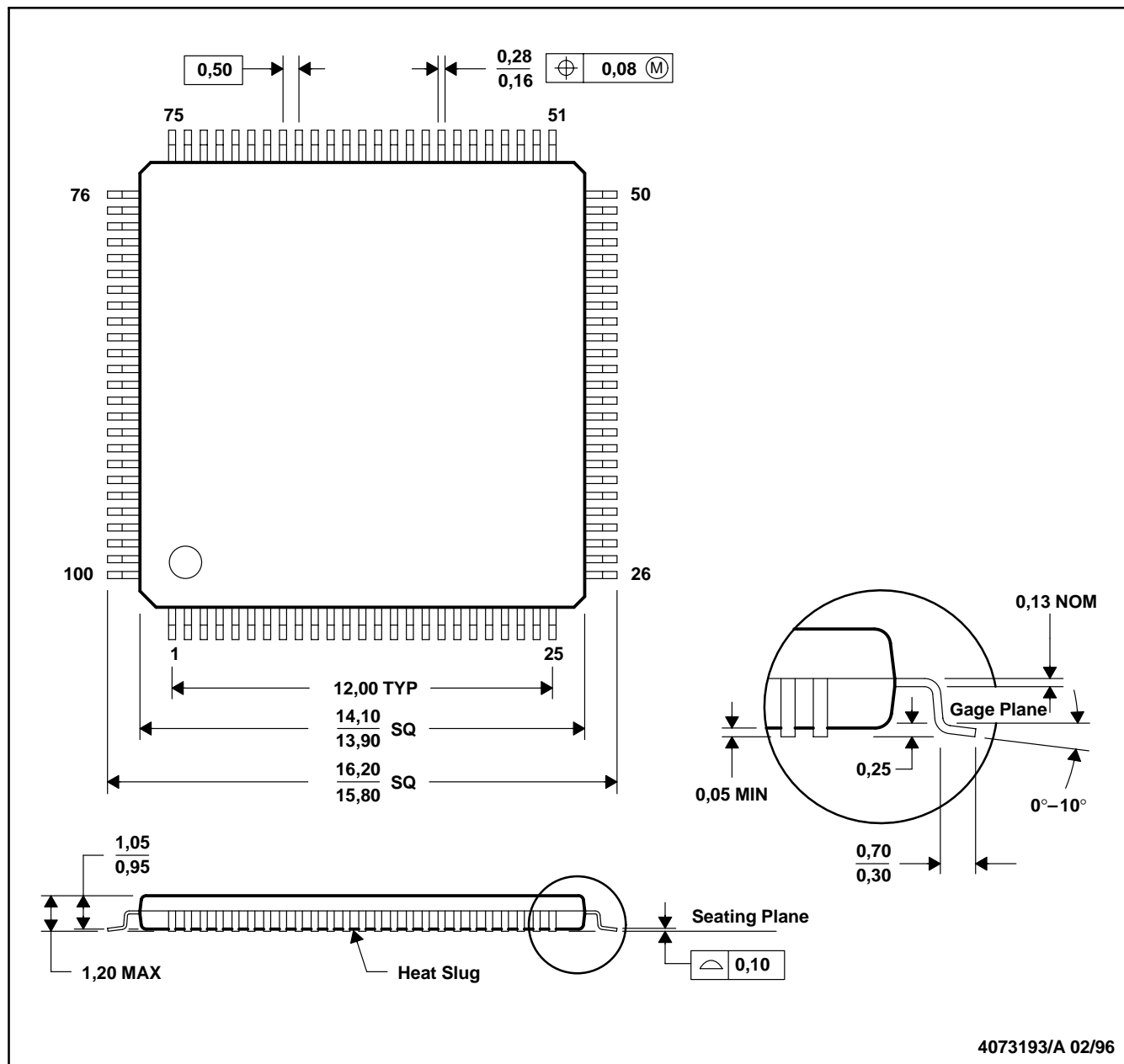


PZV (S-PQFP-G100)

PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced molded plastic package with a square exposed heat slug (HSL) on bottom.

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